# Panasonic

Zener Diode

# DZ2J056×0L Silicon epitaxial planar type

#### For constant voltage / For surge absorption circuit

- Features
- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: DJ or DU

#### Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C Parameter Symbol

Repetitive peak forward current	IFRM	200	mA
Total power dissipation <sup>*1</sup>	PT	200	mW
Electrostatic discharge *2	ESD	±15	kV
Junction temperature	Tj	150	О°
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

 Note)
 \*1
 Mounted on glass epoxy print board (45 mm × 45 mm × 1 mm)

 Solder in (Recommended land pattern)

\*2 Test method : IEC61000\_4\_2

(C = 150 pF, R = 330  $\Omega$ , Contact discharge : 10 times )

#### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

$\blacksquare$ Electrical Characteristics Ta = 25 °C	±3°C					
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage *1, *2	VZ	IZ = 5 mA	5.32		5.88	V
Zener operating resistance	RZ	IZ = 5 mA			40	Ω
Zener rise operating resistance	RZK	IZ = 0.5 mA			200	Ω
Reverse current	IR	VR = 2.5 V			0.5	μA
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		1.6		mV/°C

Rating

Unit

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. Absolute frequency of input and output is 5 MHz.

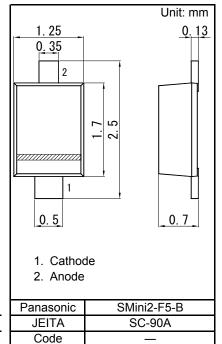
3. \*1 The temperature must be controlled 25 °C for VZ mesurement.

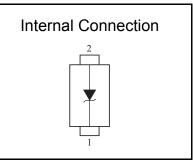
VZ value measured at other temperature must be adjusted to VZ (25 °C).

\*2 VZ guaranted 20 ms after current flow Rank classification

\*3 Tj = 25 °C to 150 °C

k classification					
Code	М	0			
Rank	М	No-rank			
VZ	5.48 to 5.76	5.32 to 5.88			
Marking symbol	DU	DJ			

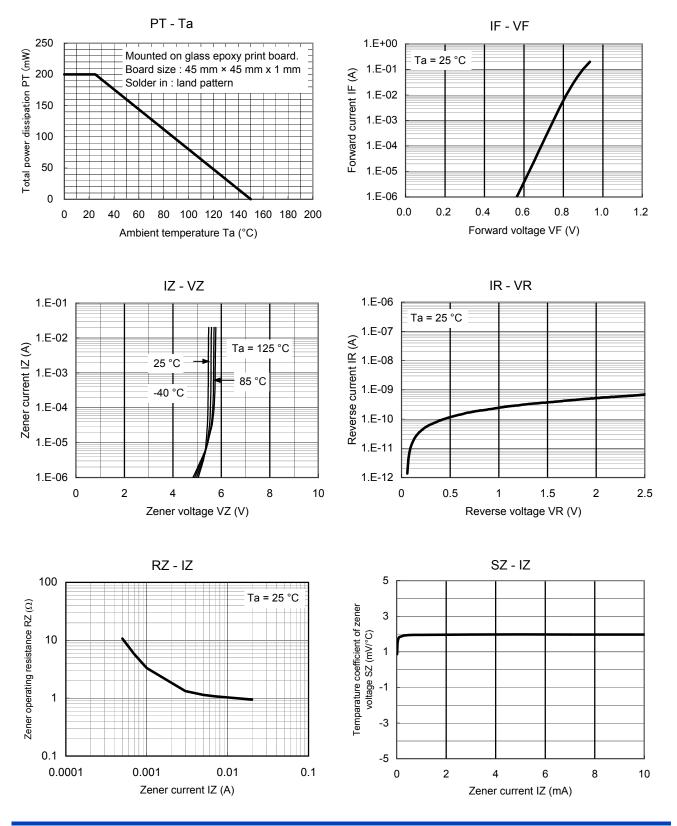






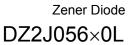
Zener Diode DZ2J056×0L

## Technical Data (reference)

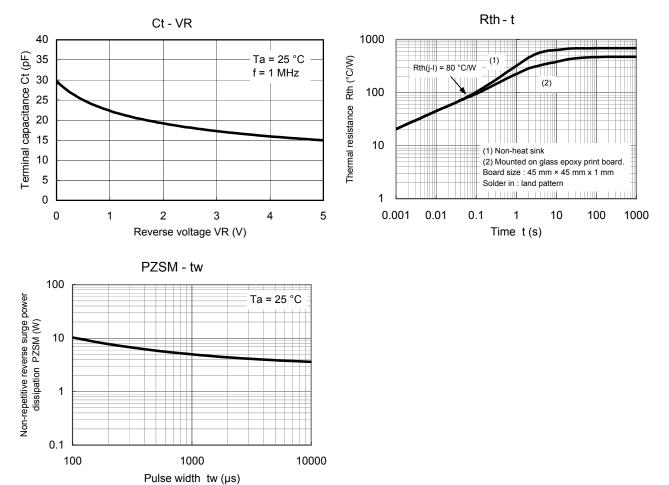


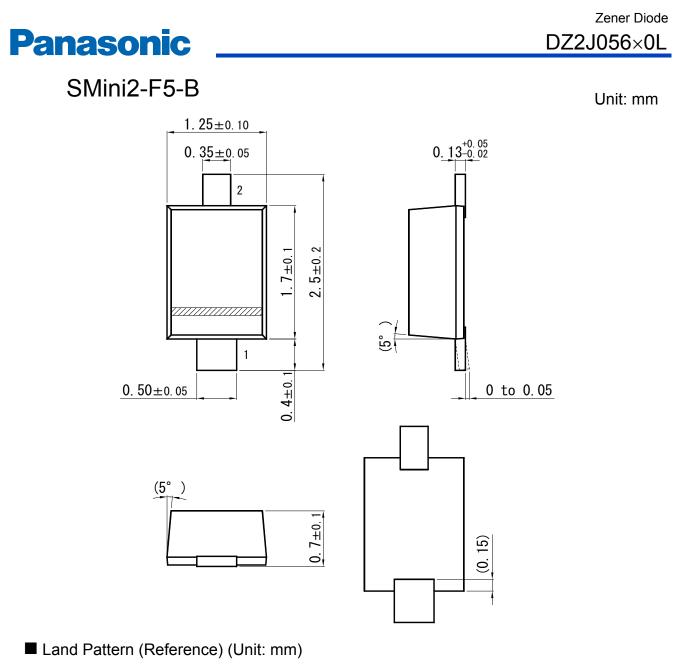
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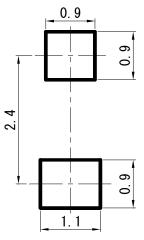
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# Technical Data (reference)







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